

3.3/5 V ECL Differential Phase-Frequency Detector

MC100LVEL40

Description

The MC100LVEL40 is a three state phase frequency–detector intended for phase–locked loop applications which require a minimum amount of phase and frequency difference at lock. Advanced design significantly reduces the dead zone of the detector. For proper operation, the input edge rate of the R and V inputs should be less than 5 ns. The device is designed to work with a 3.3 V power supply.

When the reference (R) and the feedback (FB) inputs are unequal in frequency and/or phase the differential up (U) and down (D) outputs will provide pulse streams which when subtracted and integrated provide an error voltage for control of a VCO.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

For application information, refer to AND8040/D, “Phase Lock Loop Operation.”

The 100 Series Contains Temperature Compensation.

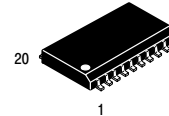
Features

- 250 MHz Typical Bandwidth
- PECL Mode Operating Range:
 $V_{CC} = 3.0 \text{ V to } 5.5 \text{ V with } V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range:
 $V_{CC} = 0 \text{ V with } V_{EE} = -3.0 \text{ V to } -5.5 \text{ V}$
- Internal Input Pulldown Resistor
- This Devices are Pb–Free, Halogen Free and are RoHS Compliant



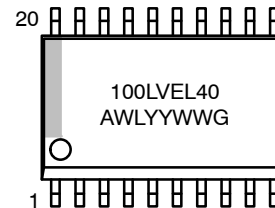
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SO-20
DW SUFFIX
CASE 751D

MARKING DIAGRAM



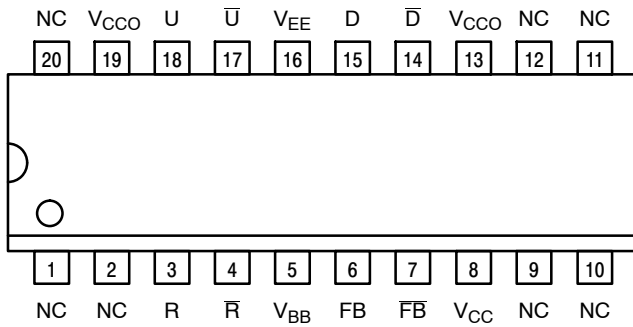
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb–Free Package

*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping
MC100LVEL40DWG	SOIC–20 (Pb–Free)	38 Units / Tube

MC100LVEL40



Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 20-Lead Pinout (Top View)

Table 1. PIN DESCRIPTION

PIN	FUNCTION
U, \bar{U}	ECL Up Differential Outputs
D, \bar{D}	ECL Down Differential Outputs
FB, \bar{FB}	ECL Feedback Differential Inputs
R, \bar{R}	ECL Reference Differential Inputs
V _{BB}	Reference Voltage Output
V _{CC} , V _{CCO}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect

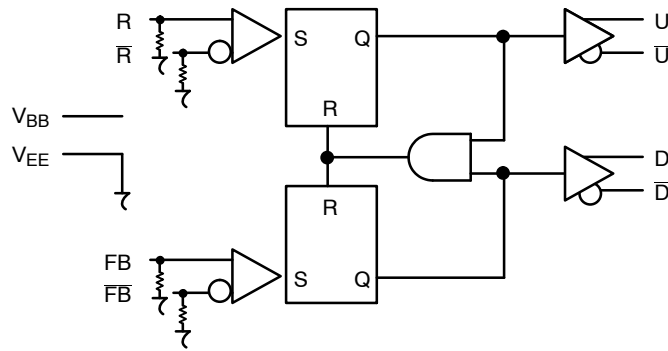


Figure 2. Logic Diagram

Table 2. ATTRIBUTES

Characteristics	Value
ESD Protection Human Body Model	> 2 kV
Moisture Sensitivity (Note 1)	Pb-Free Pkg
SOIC-20	Level 3
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	356 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note [AND8003/D](#).

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Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-8 to 0	V
V _I	PECL Mode Input Voltage	V _{EE} = 0 V	V _I ≤ V _{CC}	6 to 0	V
	NECL Mode Input Voltage	V _{CC} = 0 V	V _I ≥ V _{EE}	-6 to 0	V
I _{out}	Output Current	Continuous Surge		50	mA
				100	
I _{BB}	V _{BB} Sink/Source			±0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm	SOIC-20	90	°C/W
		500 lfpm	SOIC-20	306	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-20	30 to 35	°C/W
T _{sol}	Wave Solder (Pb-Free)			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. LVPECL DC CHARACTERISTICS V_{CC} = 3.3 V, V_{EE} = 0 V (Note 2)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I _{EE}	Power Supply Current		38	45		38	47		38	47	mA
V _{OH}	Output HIGH Voltage (Note 3)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 3)	1470	1605	1745	1490	1595	1380	1490	1595	1680	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V _{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Note 7) V _{pp} < 500 mV V _{pp} ≥ 500 mV	1.3		3.3	1.2		3.3	1.2		3.3	V
		1.5		3.3	1.4		3.3	1.4		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μA
I _{IL}	Input LOW Current Others R, FB	0.5			0.5			0.5			μA
		-300			-300			-300			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ± 0.3 V.
- Outputs are terminated through a 50 Ω resistor to V_{CC} - 2 V.
- V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{ppmin} and 1 V.

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Table 5. LVNECL DC CHARACTERISTICS $V_{CC} = 0\text{ V}$; $V_{EE} = -3.0\text{ V}$ (Note 5)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		38	45		38	47		38	47	mA
V_{OH}	Output HIGH Voltage (Note 6)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V_{OL}	Output LOW Voltage (Note 6)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V_{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Note 7) $V_{pp} < 500\text{ mV}$ $V_{pp} \geq 500\text{ mV}$	-2.0		-0.4	-2.1		-0.4	-2.1		-0.4	V
		-1.8		-0.4	-1.9		-0.4	-1.9		-0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current Others \bar{R} , \bar{FB}	0.5			0.5			0.5			μA
		-300			-300			-300			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

5. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $\pm 0.3\text{ V}$.

6. All loading with 50 Ω resistor to $V_{CC} - 2\text{ V}$.

7. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{ppmin} and 1 V.

Table 6. AC CHARACTERISTICS $V_{CC} = 3.3\text{ V}$; $V_{EE} = 0.0\text{ V}$ or $V_{CC} = 0\text{ V}$; $V_{EE} = -3.3\text{ V}$ (Note 8)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
F_{max}	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t_{PLH} t_{PHL}	Propagation Delay R to U, FB to D	430		630	450		650	480		680	ps
		1200		1400	1250		1450	1370		1590	
V_{PP}	Input Swing (Differential Configuration) (Note 9)	150		1000	150		1000	150		1000	mV
t_{JITTER}	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t_r , t_f	Output Rise/Fall Times	175		475	175		475	175		475	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

8. V_{EE} can vary $\pm 0.3\text{ V}$.

9. $V_{PP(min)}$ is minimum input swing for which AC parameters guaranteed. The device has a DC gain of ≈ 40 .

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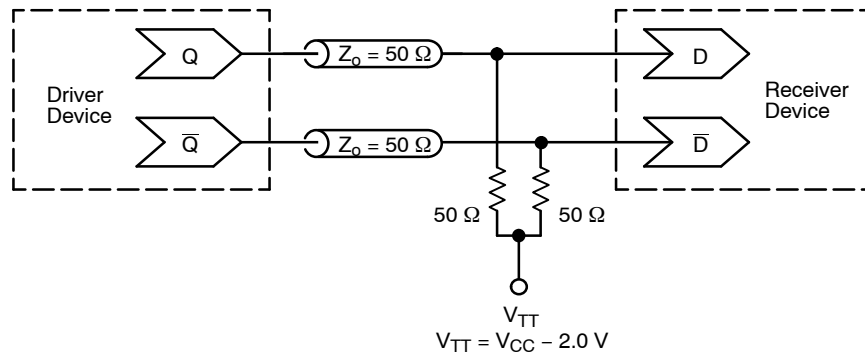


Figure 3. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

SOIC-20 WB
CASE 751D-05
ISSUE H

DATE 22 APR 2015

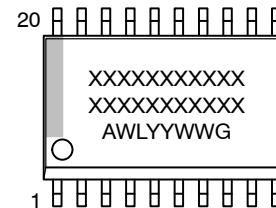


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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